L Number	Hits	Search Text	DB	Time stamp
2	4609	(257/735-738,777-786).CCLS.	USPAT	2003/01/16 15:46
3	6729	(427/372.2,375,384,385.5,386,407.1).CCLS.	USPAT	2003/01/16 15:50
4	1753	(438/612-618).CCLS.	USPAT	2003/01/16 15:50
5	3129	(((257/735-738,777-786).CCLS.) ((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow$3 re$1melt$3 flow$3) and (electrode$1 bump$1 pad$1) and (mount$3 bond$3 adhe$4 tacky glu$3)	USPAT	2003/01/16 15:55
6	2010	((((257/735-738,777-786).CCLS.) ((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow$3 re$1melt$3 flow$3) and (electrode$1 bump$1 pad$1) and (mount$3 bond$3 adhe$4 tacky glu$3)) and (resin$3 epoxy)	USPAT	2003/01/16 15:56
7	210	(((((257/735-738,777-786).CCLS.) ((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow$3 re$1melt$3 flow$3) and (electrode$1 bump$1 pad$1) and (mount$3 bond$3 adhe$4 tacky glu$3)) and (resin$3 epoxy)) and fatigue	USPAT	2003/01/16 15:57
8	171	((((((257/735-738,777-786).CCLS.) ((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow$3 re$1melt$3 flow$3) and (electrode$1 bump$1 pad$1) and (mount$3 bond$3 adhe$4 tacky glu$3)) and (resin$3 epoxy)) and fatigue) and (solidif$4 solidification densif$4 densification harden$3 cur$3)	USPAT	2003/01/16 15:59
9	103	(((((((257/735-738,777-786).CCLS.) ((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow$3 re$1melt$3 flow$3) and (electrode$1 bump$1 pad$1) and (mount$3 bond$3 adhe$4 tacky glu$3)) and (resin$3 epoxy)) and fatigue) and (solidif$4 solidification densif$4 densification harden$3 cur$3)) and (solvent flux$4)	USPAT	2003/01/16 16:27
10	914	((((((257/735-738,777-786).CCLS.) ((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow$3 re$1melt$3 flow$3) and (electrode$1 bump$1 pad$1) and (mount$3 bond$3 adhe$4 tacky glu$3)) and (resin$3 epoxy)) and (wafer$1 substrate$1) same (cut$4 dic$3 singulat$3 sever$3)	USPAT	2003/01/16 16:26
11	851	(((((((257/735-738,777-786).CCLS.) ((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow$3 re$1melt$3 flow$3) and (electrode$1 bump$1 pad$1) and (mount$3 bond$3 adhe$4 tacky glu$3)) and (resin$3 epoxy)) and (wafer$1 substrate$1) same (cut$4 dic$3 singulat$3 sever$3)) not (((((((257/735-738,777-786).CCLS.) ((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow$3 re$1melt$3 flow$3) and (electrode$1 bump$1 pad$1) and (mount$3 bond$3 adhe$4 tacky glu$3)) and (resin$3 epoxy)) and fatigue) and (solidif$4 solidification densif$4 densification harden$3 cur$3)) and (solvent flux$4))	USPAT	2003/01/16 16:26

12	344	(((((((257/735-738,777-786).CCLS.) ((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow$3 re$1melt$3 flow$3) and (electrode$1 bump$1 pad$1) and (mount$3 bond$3 adhe$4 tacky glu$3)) and (resin$3 epoxy)) and (wafer$1 substrate$1) same (cut$4 dic$3 singulat$3 sever$3)) not (((((((257/735-738,777-786).CCLS.) ((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow$3 re$1melt$3 flow$3) and (electrode$1 bump$1 pad$1) and (mount$3 bond$3 adhe$4 tacky glu$3)) and (resin$3 epoxy)) and fatigue) and (solidif$4 solidification densif$4 densification harden$3 cur$3)) and (solvent flux$4))) and (solvent flux$4)	USPAT	2003/01/16 16:29
13	252	(((((((257/735-738,777-786).CCLS.) ((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow$3 re$1melt$3 flow$3) and (electrode$1 bump$1 pad$1) and (mount$3 bond$3 adhe$4 tacky glu$3)) and (resin$3 epoxy)) and (wafer$1 substrate$1) same (cut$4 dic$3 singulat$3 sever$3)) not (((((((257/735-738,777-786).CCLS.) ((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow$3 re$1melt$3 flow$3) and (electrode$1 bump$1 pad$1) and (mount$3 bond$3 adhe$4 tacky glu$3)) and (resin$3 epoxy)) and fatigue) and (solidif$4 solidification densif$4 densification harden$3 cur$3)) and (solvent flux$4))) and (solvent flux$4)) and (fill$3 under$1fill$3)	USPAT	2003/01/16 17:00
14	20	((((((((257/735-738,777-786).CCLS.) ((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow$3 re$1melt$3 flow$3) and (electrode$1 bump$1 pad$1) and (mount$3 bond$3 adhe$4 tacky glu$3)) and (resin$3 epoxy)) and (wafer$1 substrate$1) same (cut$4 dic$3 singulat$3 sever$3)) not (((((((257/735-738,777-786).CCLS.) ((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow$3 re$1melt$3 flow$3) and (electrode$1 bump$1 pad$1) and (mount$3 bond$3 adhe$4 tacky glu$3)) and (resin$3 epoxy)) and fatigue) and (solidif$4 solidification densif$4 densification harden$3 cur$3)) and (solvent flux$4))) and (solvent flux$4)) and (fill$3 under$1fill$3)) and wafer$1 near3 level	USPAT	2003/01/16 17:07

| 15 | 232 | (((((((((257/735-738,777-786).CCLS.) ((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow$3 re$1melt$3 flow$3) and (electrode$1 bump$1 pad$1) and (mount$3 bond$3 adhe$4 tacky glu$3)) and (resin$3 epoxy)) and (wafer$1 substrate$1) same (cut$4 dic$3 singulat$3 sever$3)) not (((((((((257/735-738,777-786).CCLS.) ((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow$3 re$1melt$3 flow$3) and (electrode$1 bump$1 pad$1) and (mount$3 bond$3 adhe$4 tacky glu$3)) and (resin$3 epoxy)) and fatigue) and (solidif$4 solidification densif$4 densification harden$3 cur$3)) and (solvent flux$4))) and (solvent flux$4)) and (fill$3 under$1fill$3)) not (((((((((257/735-738,777-786).CCLS.) ((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow$3 re$1melt$3 flow$3) and (electrode$1 bump$1 pad$1) and (mount$3 bond$3 adhe$4 tacky glu$3)) and (resin$3 epoxy)) and (wafer$1 substrate$1) same (cut$4 dic$3 singulat$3 sever$3)) not (((((((((257/735-738,777-786).CCLS.) ((427/372.2,375,384,385.5,386,407.1).CCLS.) ((438/612-618).CCLS.)) and (reflow$3 re$1melt$3 flow$3) and (electrode$1 bump$1 pad$1) and (mount$3 bond$3 adhe$4 tacky glu$3)) and (resin$3 epoxy)) and fatigue) and (solidif$4 solidification densif$4 densification harden$3 cur$3)) and (solvent flux$4))) and (solvent flux$4)) and (fill$3 under$1fill$3)) and wafer$1 near3 level) | USPAT | 2003/01/16 17:07 |